



VMDSEMI

**VUPB003R021NA**

**Datasheet**



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**General Description**
**Symbol**

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	$I_D$
30V	2.1mΩ@10V	150A
	2.8mΩ@4.5V	

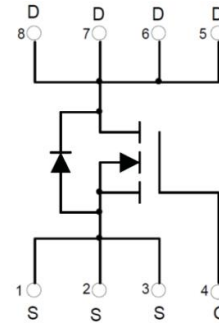
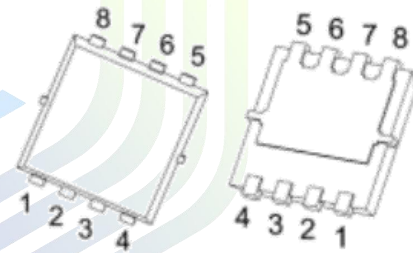


Figure 1 Symbol of VUPB003R021NA

**Features**

- Trench Technology Power MOSFET
- Low Gate Resistance
- Low  $R_{DS(ON)}$
- 100% UIS Tested

**Package Type**

**PDFN5X6-8L**
**Application**

- Power Switch Application
- DC/DC Converters

Figure 2 Package Type of VUPB003R021NA

**Ordering Information**

Product Name	Package
VUPB003R021NA	PDFN5X6-8L

**Absolute Maximum Ratings** ( $T_A = 25\text{ °C}$ , unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DSS}$	30	V
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V
Continuous Drain Current <sup>Note1</sup>	$I_D$	150	A
Pulsed Drain Current <sup>Note2</sup>	$I_{DM}$	600	
Single Pulsed Avalanche Energy <sup>Note3</sup>	$E_{AS}$	689	mJ
Avalanche Current <sup>Note3</sup>	$I_{AS}$	52.5	A
Total Power Dissipation <sup>Note5</sup>	$P_D$	56.8	W
Total Power Dissipation <sup>Note5</sup>	$P_D$	2.5	W
Junction Temperature	$T_J$	150	°C
Storage Temperature	$T_{STG}$	-55 to 150	°C

**Thermal Resistance**

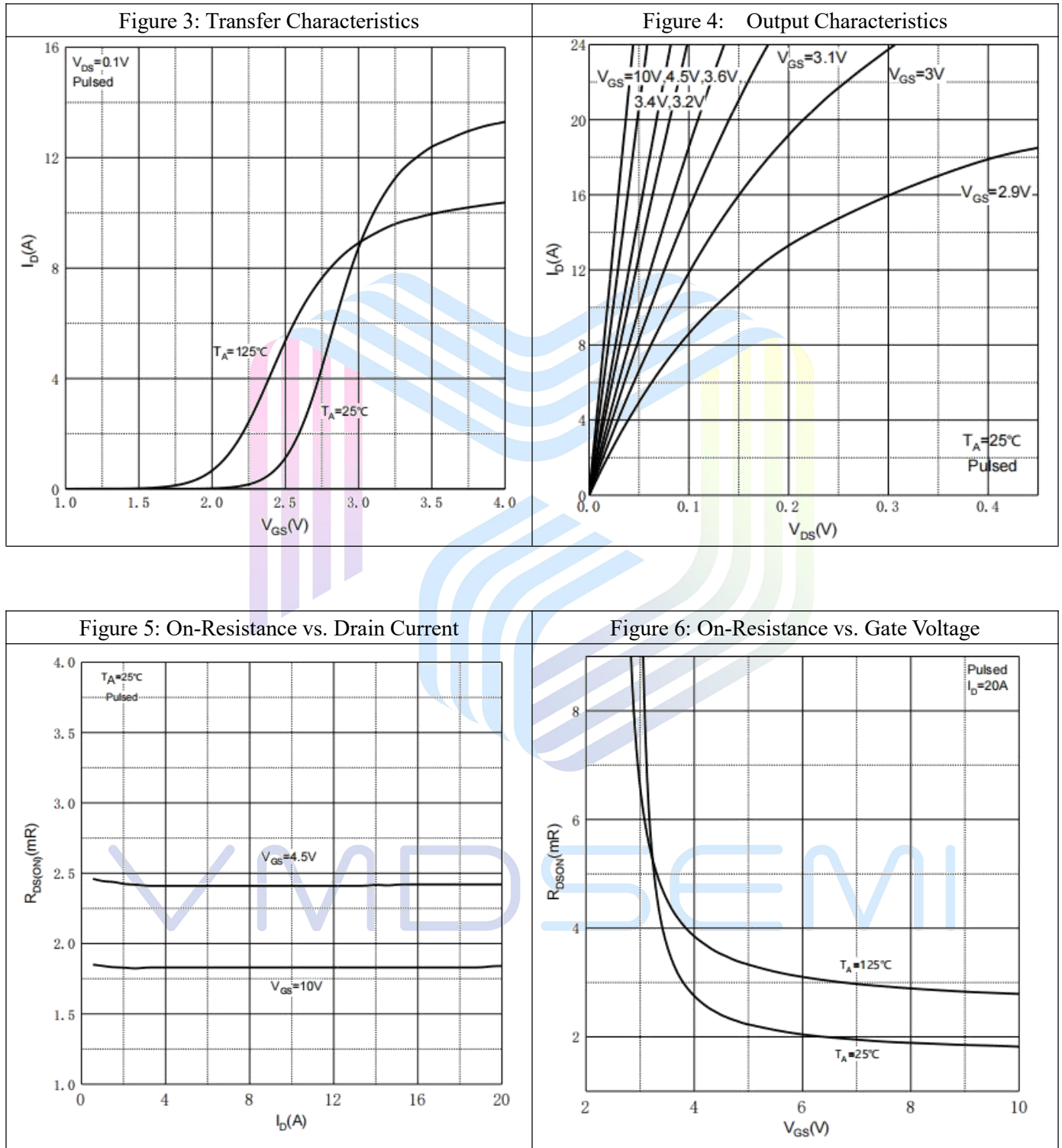
Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient <sup>Note6</sup>	$R_{\theta JA}$		50		°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$		2.2		°C/W

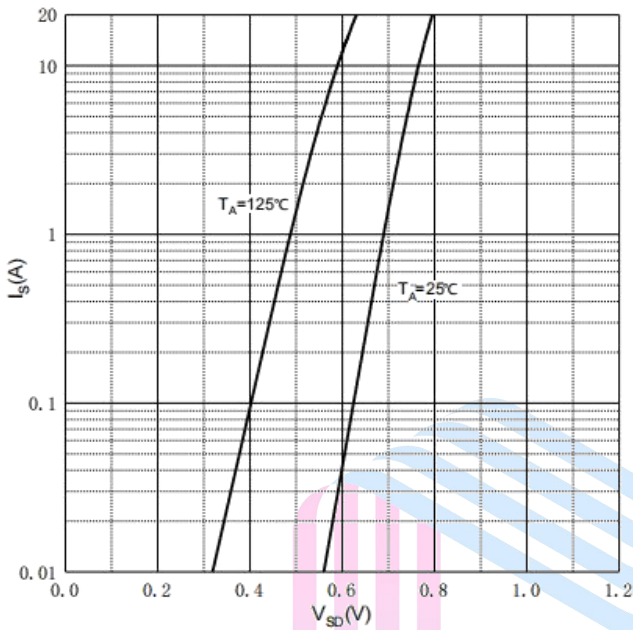
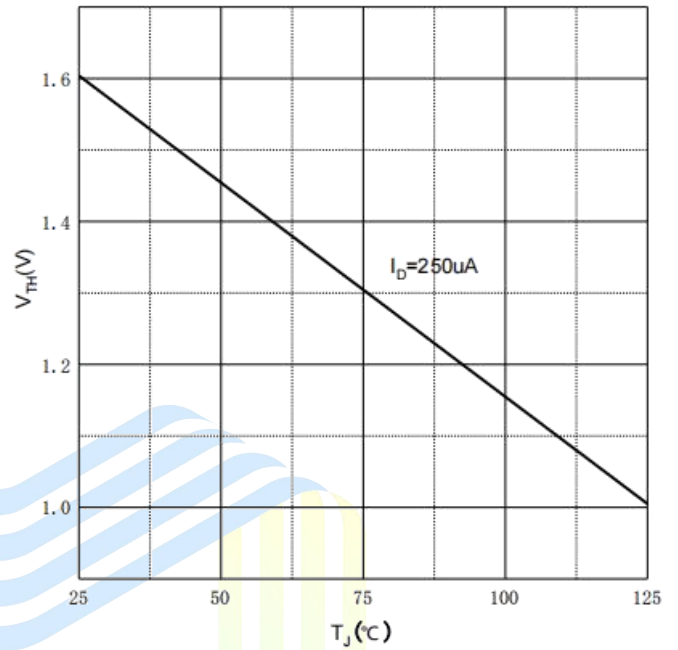
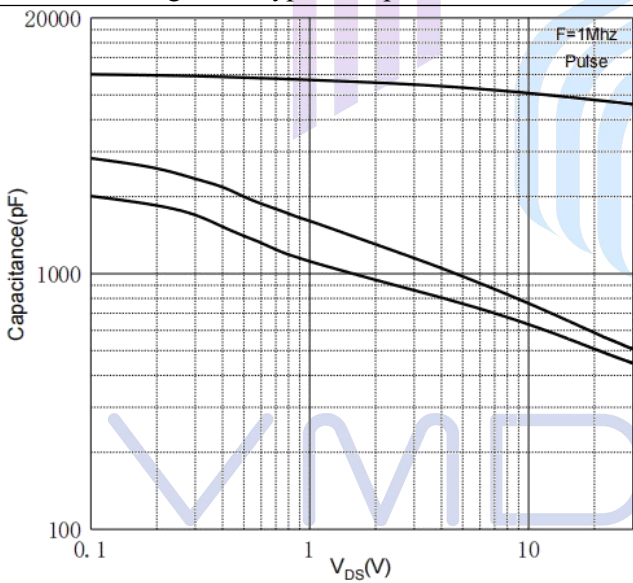
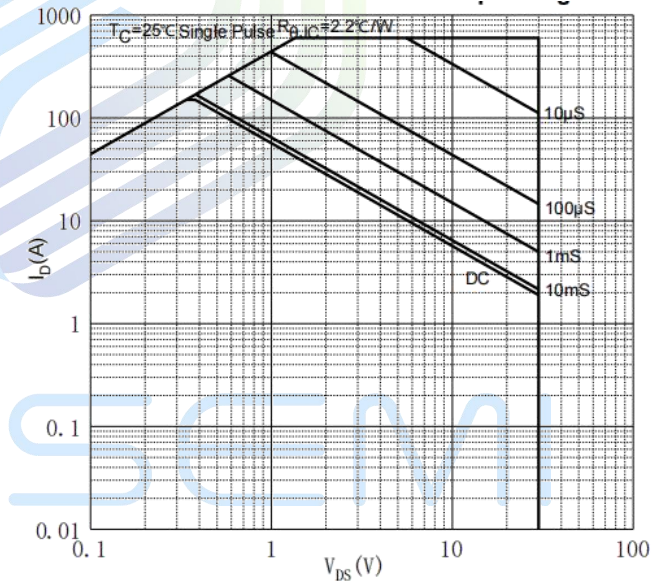
**Electrical Characteristics** ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	30			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=30V, V_{GS}=0V$			1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS}=0V$			$\pm 100$	nA
Gate Threshold Voltage <sup>Note4</sup>	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.5	3.0	V
Static Drain-Source On-Resistance <sup>Note4</sup>	$R_{DS(on)}$	$V_{GS}=10V, I_D=20A$		1.5	2.1	mΩ
		$V_{GS}=4.5V, I_D=10A$		2.1	2.8	
Forward Transconductance <sup>Note4</sup>	$g_{FS}$	$V_{DS}=5V, I_D=20A$		100		S
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=15V$		5186		pF
Output Capacitance	$C_{OSS}$	$V_{GS}=0V$		660		pF
Reverse Transfer Capacitance	$C_{RSS}$	$f=1MHz$		555		pF
Total Gate Charge	$Q_g$	$V_{DS}=15V$		105		nC
Gate-Source Charge	$Q_{gs}$	$V_{GS}=10V$		12.1		
Gate-Drain Charge	$Q_{gd}$	$I_D=20A$		25.6		
Gate Resistance	$R_g$	$f=1MHz, \text{Open drain}$		1.5		Ω
<b>Switching Parameters</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=15V$		12.5		ns
Turn-on Rise Time	$t_r$	$V_{GS}=10V$		6		
Turn-off Delay Time	$t_{d(off)}$	$R_L=0.75\Omega$		47		
Turn-off Fall Time	$t_f$	$R_G=3\Omega$		10.5		
<b>Diode Characteristics</b>						
Diode Forward Voltage <sup>Note4</sup>	$V_{SD}$	$V_{GS}=0V, I_S=10A$			1.2	V

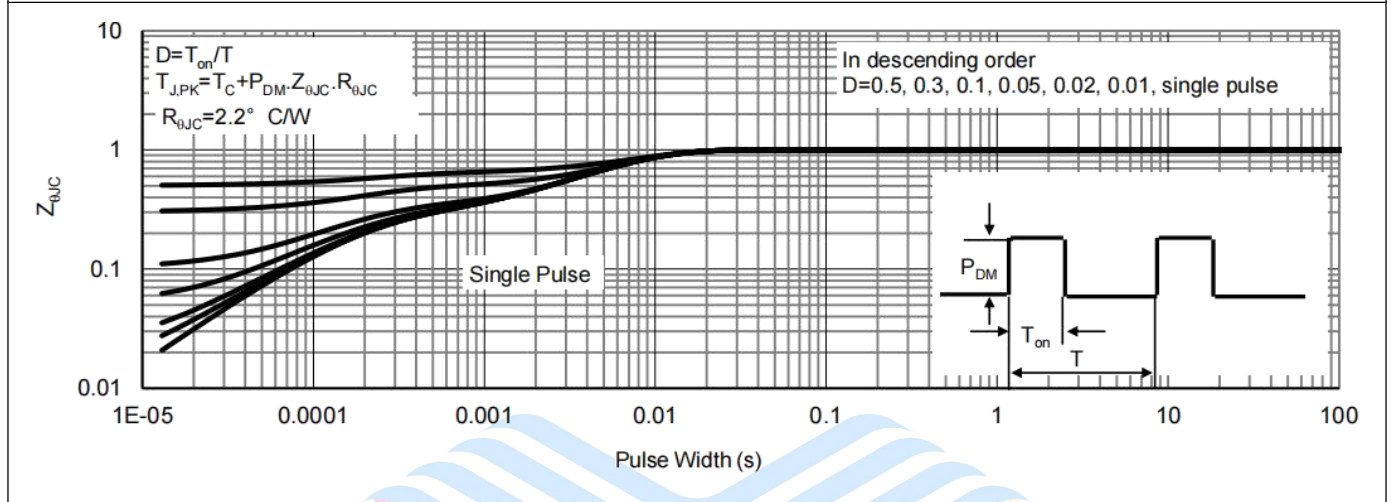
Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width  $\leq 10\mu s$ , duty cycle  $\leq 1\%$ .
- 3.EAS condition:  $V_{DD}=15V, V_{GS}=10V, L=0.5mH, R_G=25\Omega$  Starting  $T_J=25^\circ C$ .
- 4.Pulse Test : Pulse Width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
- 5.The power dissipation  $P_D$  is limited by  $T_{J(MAX)}=150^\circ C$ .And device mounted on a large heatsink
- 6.Device mounted on  $1in^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ C$ .

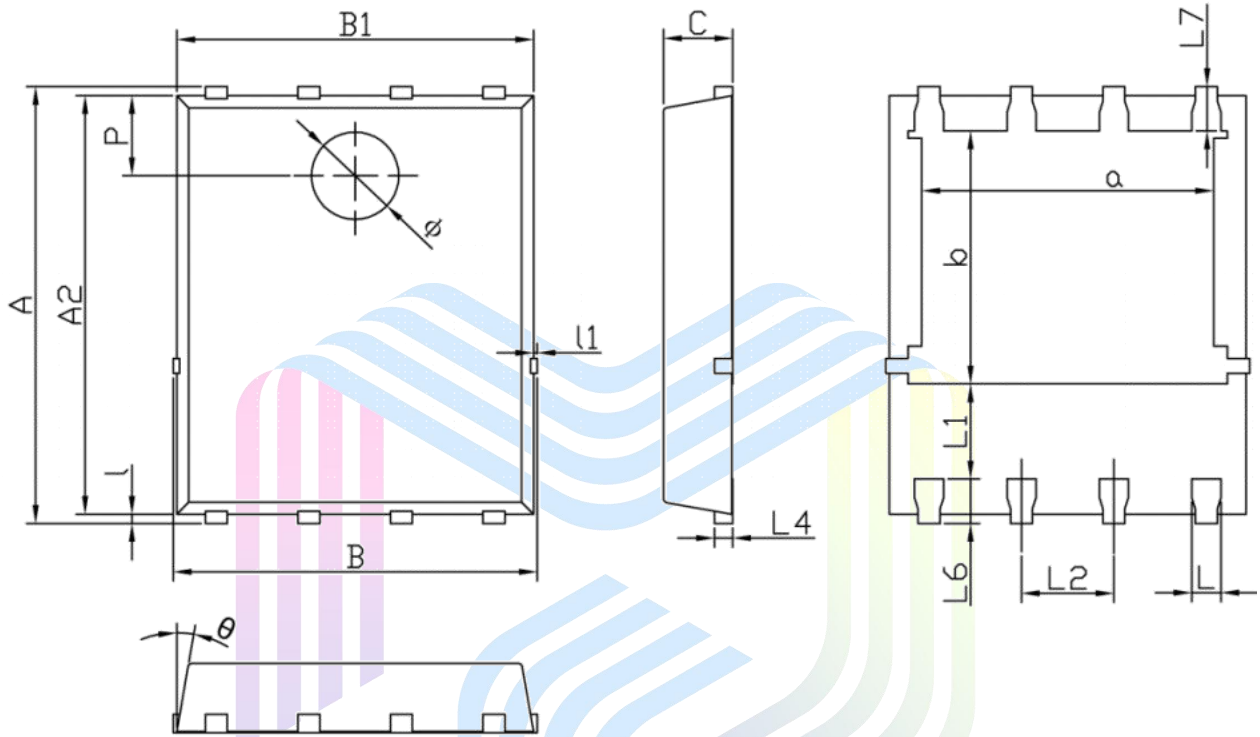
**Typical Performance Characteristics**


**Figure 7: Body Diode Characteristics**

**Figure 8: Threshold Voltage**

**Figure 9: Typical Capacitance**

**Figure 10: Safe Operation Area**




**Figure 11: Normalized Maximum Transient Thermal Impedance**



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**Mechanical Dimensions:**
**PDFN5X6-8L Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	5.900	6.100	0.232	0.240
a	3.910	4.110	0.154	0.162
A2	5.700	5.800	0.224	0.228
B	4.900	5.100	0.193	0.201
b	3.370	3.570	0.133	0.141
B1	4.800	5.000	0.189	0.197
C	0.900	1.000	0.035	0.039
L	0.350	0.450	0.014	0.018
l	0.060	0.200	0.002	0.008
L1	1.100	-	0.043	-
l1	-	0.100	-	0.004
L2	1.170	1.370	0.046	0.054
L4	0.210	0.340	0.008	0.013
L6	0.510	0.710	0.020	0.028
L7	0.510	0.710	0.020	0.028
P	1.000	1.200	0.039	0.047
Φ	1.100	1.300	0.043	0.051
θ	8°	12°	8°	12°



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